SIMPLIFYING Thermal Conductivity (k)

FAST, ACCURATE TESTING

0 to 500 W/mK in seconds

WIDE TEMPERATURE RANGE

-50 °C to 200 °C With option to extend to 500 °C

NO SAMPLE PREPARATION

Unlimited sample size

NON-DESTRUCTIVE

Leaves sample unaltered

EASY-TO-USE

No user-calibration required

HIGHLY VERSATILE

Tests solids, liquids, powders and pastes

MODULAR

Configurable to meet a range of needs and budget. Option to pair with C-Therm Dilatometer.





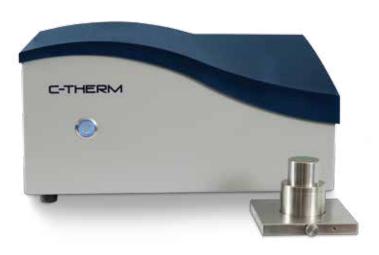
SIMPLIFYING

THERMAL CONDUCTIVITY

C-Therm's patented sensor technology makes thermal conductivity simpler and more accessible to measure. There is simply no faster or easier way to measure thermal conductivity and effusivity.

With the C-Therm TCi there is no complex regression analysis necessary as with other transient methods. No special sample preparation is required and there is no need to measure additional sample material properties such as heat capacity.

The TCi is provided with one versatile sensor for testing all types of materials; including solids, liquids, powders and pastes. A second sensor can be added for increased capacity.



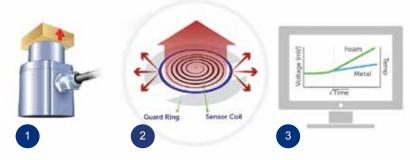
The testing procedure is noninvasive; samples remain unaltered and reusable. The system offers users exceptional versatility in being able to operate in a variety of environments, including thermal chambers, high pressure vessels and glove boxes. Fast and accurate testing made easy!

Principles of Operation

The C-Therm TCi employs the patented Modified Transient Plane Source (MTPS) technique. The one-sided, interfacial heat reflectance sensor applies a momentary constant heat source to the sample. Thermal conductivity and effusivity are measured directly, providing a detailed overview of the thermal characteristics of the sample.



How It Works



The TCi is factory-calibrated for directly measuring both thermal conductivity (k) & thermal effusivity:



Thermal Conductivity

Where: $k = thermal\ conductivity\ (W/m \cdot K)$ $\rho = density\ (kg/m^3)$ $c_* = heat\ capacity\ (J/kg \cdot K)$ A known current is applied to the sensor's spiral heating element, providing a small amount of heat.

The sensor's guard ring is fired simultaneously supporting a one-dimensional heat exchange between the primary sensor coil and the sample. The current applied to the coil results in a rise in temperature at the interface between the sensor and sample, which induces a change in the voltage drop of the sensor element.

The increase in temperature is monitored with the sensor's voltage and is used to determine the thermo-physical properties of the sample. The thermal conductivity is inversely proportional to the rate of increase in the sensor voltage (or temperature increase). The voltage rise will be steeper for lower thermal conductivity materials (e.g. foam) and flatter for higher thermal conductivity materials (e.g. metal). Results are reported in real-time making thermal conductivity measurement fast and easy.

COMPARISON

FASTER, EASIER, MORE VERSATILE



C-Therm TCi (Modified Transient Plane Source)



Guarded Hot Plate



Transient Plane Source



LaserFlash Diffusivity

PRICING	\$	\$\$	\$\$	\$\$\$
Material Testing Capabilities	Solids, Liquids, Powders, Pastes	Solids	Solids, Liquids	Solids
Maximum	Unlimited	24" x 24" (600 x 600 mm)	Two Identical Samples Unlimited	0.5" diameter (12.4 mm 0.004" thick (1 mm)
Minimum	0.67" diameter (17 mm)	6" x 6" (150 x 150 mm)	Two Identical Samples 1" x 1" (25 x 25 mm)	0.5" diameter (12.4 mm 0.004" thick (1 mm)
SAMPLE CONFIGURATI	ION			
Temperature Range (℃)	-50 °C to 200 °C With option to extend to 500 °C	-100 °C to 1400 °C	-100 °C to 700 °C	-150 ℃ to 2800 ℃
k-Range (W/mK)	0 – 500	0 – 2	0 – 100 (100 – 500 requires C _p)	$0-500$ (requires density & C_p)
RANGE				
Method Development	©	⊕⊗	⊕ ★	9
Non-Destructive	Yes	No	No	No
Training Time	Minimal	Moderate	Significant**	Extensive
Testing Time	Seconds	Hours	Minutes	Hours*
Sample Preparation	None Required	Extensive	Some	Extensive

¹ Based on publicly available information and feedback from users.

^{*} Calculation of thermal conductivity from Laser Flash Diffusivity Measurement requires the additional following material properties: heat capacity (C_p) density, and coefficient of thermal expansion.

** Traditional Transient Plane Source requires iterative testing to obtain the correct experimental parameters in terms of power flux, test time, and sizing of sensor necessary to obtain accurate results.

MODULAR

SCALABLE SOLUTIONS

ACCESSORIES



Compression Test Accessory (CTA)
Compression of sample material
increases the density and impacts the
effective thermal conductivity of the material.
It is important that the level of compaction
is controlled and representative of the
application conditions of the material.
C-Therm's Compression Test Accessory

(CTA) enables researchers testing such materials to precisely control the densification in providing highly reproducible results that better reflect the effective thermal conductivity. The CTA is particularly recommended to users testing textiles/fabrics, insulation batting, thermal interface materials, and powders.



High Pressure Cell (HPC)

C-Therm offers a range of high pressure cells to safely characterize the thermal conductivity of samples under elevated pressure environments up to 2000 PSI (~138 bar). C-Therm's HPCs are popular with researchers in the Oil & Gas, Nuclear and Fuel Cell industries.



Tenney Jr. Thermal Chamber
The TPS Tenney Jr. Thermal
Chamber is recommended to
users who wish to measure the
thermal conductivity at non-ambient
temperatures, from -50 °C to
200 °C. C-Therm's TCi software

enables direct control of the thermal chamber, bypassing manual operation and allowing users to pre-program their desired temperature profile and walk away!



Small-Volume Test Kit (SVTK)

The Small-Volume Test Kit was originally developed with the US Navy Surface Warfare Division specifically for testing energetic materials. The effectiveness of the accessory in reducing convection effect on testing samples make

it ideal for characterizing the thermal conductivity of liquid samples. The SVTK is commonly applied in testing nano and heat transfer fluids, as well as emulsions.

DILATOMETRY MODULE

Dilatometry provides key expansion and shrinkage properties of materials under defined temperatures.

TEMPERATURE RANGE	Room Temperature to 1600 °C	
TEMP. RESOLUTION	0.1 °C	
MAX DISPLACEMENT	4 mm	
ΔI RESOLUTION	1.25 nm/digit	
ATMOSPHERE	Air, Vacuum, Inert Gas	
SAMPLE DIMENSIONS	10 to 50 mm long x max ф12 mm	
SAMPLE HOLDER	Fused Silica, Alumina	
CONFIGURATIONS	Single or Dual Rod LVDT System 1200 °C or 1600 °C furnace	
HEATING ELEMENT	FeCrAI, SiC	
RATE OF INCREASE (°C)	1 °C/min up to 50 °C/min	



C-Therm's latest generation TCi offers an innovative new option to pair the controller with an optional dilatometer. This offers researchers significant savings in leveraging commonalities of the TCi control electronics while expanding the platform's capabilities to dilatometry.

THERMAL EXPANSION • FIRING • PHASE TRANSITION SHRINKAGE • SINTERING

VERSATILE

EASILY TEST SOLIDS, LIQUIDS, POWDERS AND PASTES

APPLICATIONS



Thermal Interface Materials



Explosives



Textiles



Thermoelectric



Rubber and



Concrete and Asphalt



Oil & Gas



Metal Hydrides





Heat Transfer Fluids



Batteries



Geological



Thin Films



Nanomaterials



Insulation



Nuclear



LED Lighting



C-Therm has provided a breakthrough in the characterization of critical performance attributes of conductive polymers used in electronics and automotive industries. The main advantage the technique offers is the flexibility to test a wide range of sample geometries. As an example, clients at a large polymer producer use the test samples from their tensile testing regimen to also test the in-plane and through-plane thermal conductivity with the C-Therm TCi. There is no longer the need to destructively machine or form specific sample sizes/dimensions to test thermal conductivity!

Powders: From Explosives to Ink Toners

The C-Therm TCi is being used to safely test the stability, degradation, and shelf life of explosives because it is the only instrument engineered for evaluating the thermal conductivity of powders safely. Sample volumes are as small as 1.25 ml. This is also critical to a rapidly growing client base in metal hydrides, where materials are expensive and available in low quantities. The technology is also migratable to manufacturing environments as a cost-effective way to monitor powder processes for moisture and homogeneity.

Pastes: Keeping the Hottest Electronics Cool

The faster and smaller microprocessors become, the more heat they generate. C-Therm's TCi is providing vital insights into the development of all materials that contribute to the overall thermal budget, including thermal interface materials such as thermal grease and gap pads. These materials are typically compressible and the thermal conductivity varies with changes in the densification of the material. Clients use the C-Therm Compression Test Accessory (CTA) to precisely control the compaction of the sample in producing results reflective of the actual application conditions for the material.

Liquids: Under Pressure

The C-Therm TCi is helping manufacturers improve the heat transfer properties of liquids. C-Therm is unique in offering the capability to accurately measure the thermal conductivity of liquids; the short test time (<1 second) and small sample volume requirements negate the convective errors typical in liquid testing with traditional techniques. As an example, clients in the Oil & Gas field use C-Therm's High Pressure Cell (HPC) accessory in measuring the impact of elevated atmospheric conditions and temperature on the thermal conductivity of fluids.







PROVEN

For over a decade, C-Therm's innovative sensor technology has been pioneering the way for many of the world's most prominent manufacturers, research facilities, and academic institutions to test and measure thermal properties of materials.



The technology behind the C-Therm TCi represents a paradigm shift in thermal conductivity measurement and earned the inventor behind the technology the Manning Innovation Principle Award and an R&D 100 Award. These coveted awards are given to the top global innovators, and place C-Therm in the distinguished company of such other winners as the developers of the ATM, Polaroid™ and anti-lock brakes.



Since its launch, C-Therm's unique technology has evolved to new levels of accuracy, speed, and flexibility. Today, it is being used around the globe for R&D, quality control, and on-line production monitoring in a wide range of industries.

C-THERM TCI SPECIFICATIONS	
Thermal Conductivity Range	0 to 500 W/mK
Test Time	0.8 to 3 seconds
Minimum Sample Testing Size	17 mm diameter
Maximum Sample Testing Size	Unlimited
Test Method	Modified Transient Plane Source (MTPS)
ASTM	D7984
Minimum Thickness	Nominally 0.5 mm, dependent on thermal
	conductivity of material
Maximum Thickness	Unlimited
Temperature Range	-50 °C to 200 °C
	With option to extend to 500 °C
Precision	Typically better than 1%
Accuracy	Better than 5%
Extra Hook-Ups Required	None
Software	Intuitive Windows®-based software interface. Easy
	export to Microsoft Excel®. Additional functionality
	offers indirect, user-input capabilities for a number
	of other thermo-physical properties including:
	Thermal Diffusivity
	Heat Capacity
	• Density
Input Power	110-230 VAC 50-60 Hz
Certifications	FCC, CE, CSA

For more information, contact:



North America: 1-877-827-7623 International: 1-506-457-1515

info@ctherm.com | www.ctherm.com

COMPANIES AND ORGANIZATIONS USING C-THERM'S PATENTED TECHNOLOGY:

NASA

University of California (Berkely)

Philips

Kodak

Averv

3M

Philip Morris

Astra Zeneca

US Navy

Patheon

Universidade de Aveiro

Raytheon

Corning

Engelhard

Universidade Federal de Santa Caterina

Wyeth

Stowe Woodward

INSA

Dow Corning

Exxon Mobil

Hewlett Packard

NRC

Liberec University

National University of Singapore

Petrobas

Henkel

Nanocomposix

Canadian Explosives Research Lab